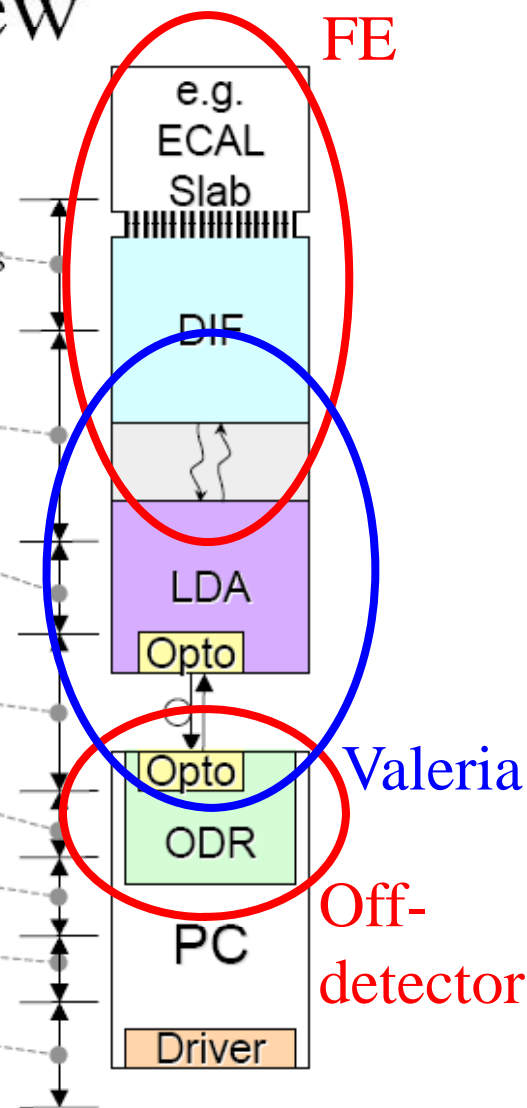

Status of UK Work on FE and Off-Detector DAQ

Paul Dauncey

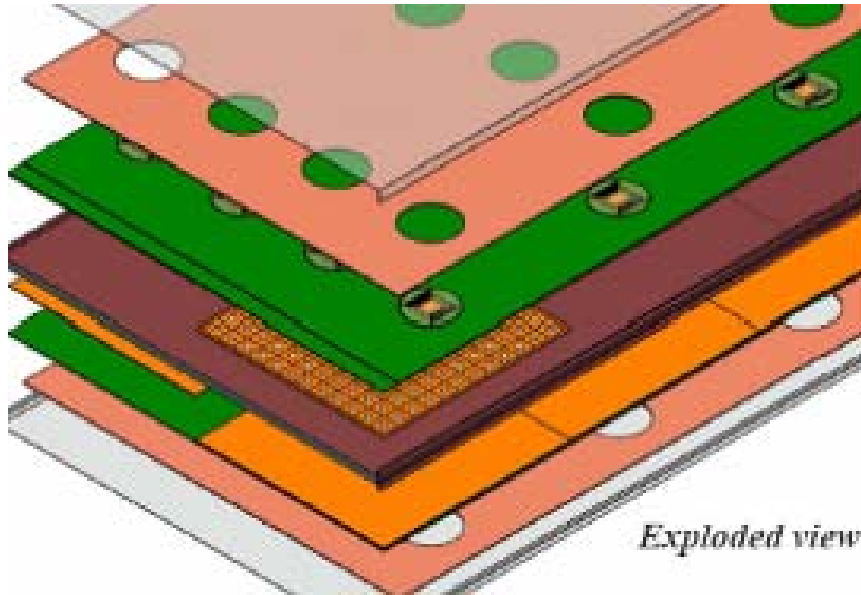
For the CALICE-UK DAQ groups:
Cambridge, Manchester, Royal
Holloway, UCL

DAQ Overview

- **Detector Interface (DIF)**
 - Sub-detector specific, in conjunction with detector groups
- **DIF to LDA**
 - Generic, Copper links (25Mbit)
- **Link/Data Aggregator (LDA)**
 - Data format
 - Clock/Commands fan-out
- **LDA to ODR opto-links**
- **Off-Detector Receiver (ODR)**
- **ODR to disk**
 - PCI-Express driver software
- **Local Software DAQ**
- **Full blown Software DAQ**



ECAL slab design

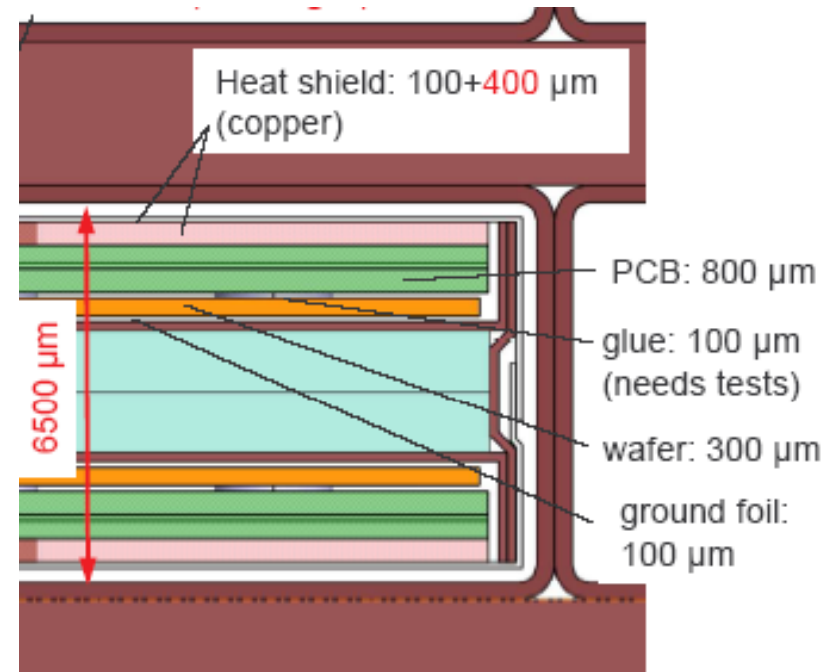


- Constraints on data paths:

- Limited space (800 μm PCB thickness)
- Tight power budget ($\ll 0.3\text{W}$)
- Long slabs ($\sim 1.6\text{m}$)

- Technology choices:

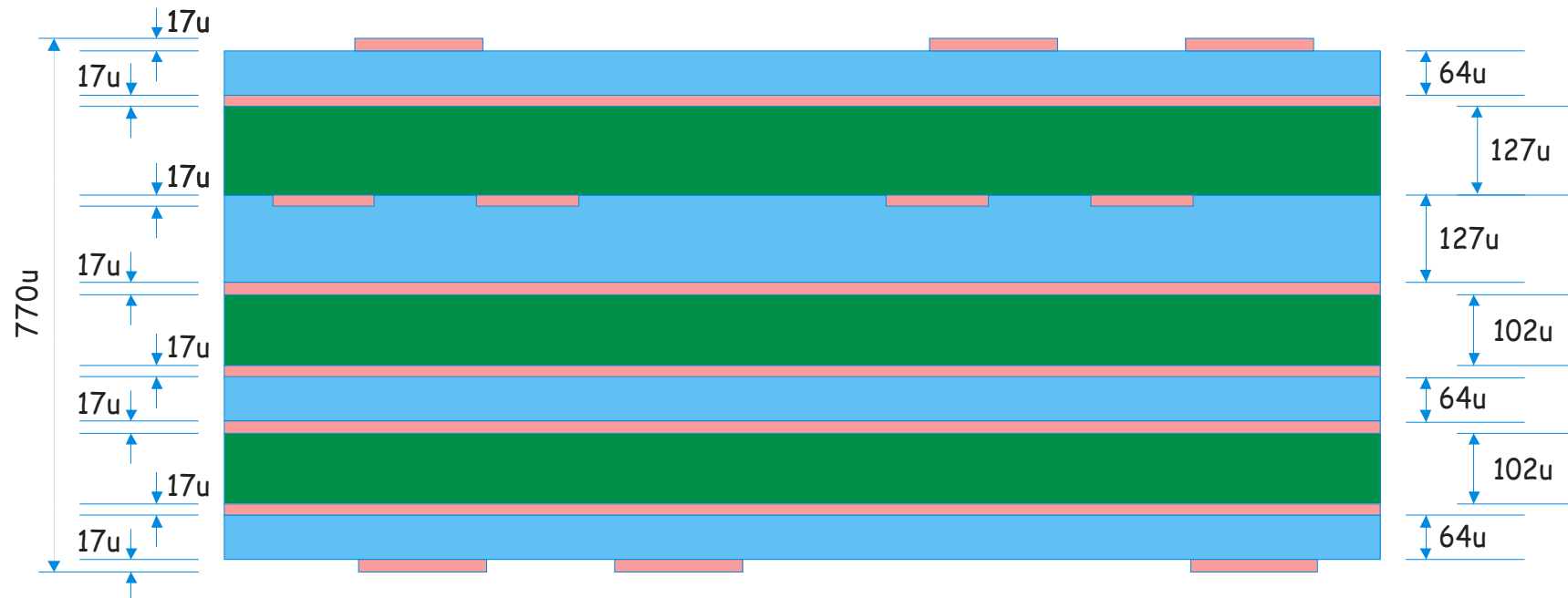
- VFE chip on board; build slab in segments (panels) to conserve yield
- Joint between PCBs must be zero height; novel interconnect needed
- CMOS signalling where possible for low power consumption



Slab panel PCB

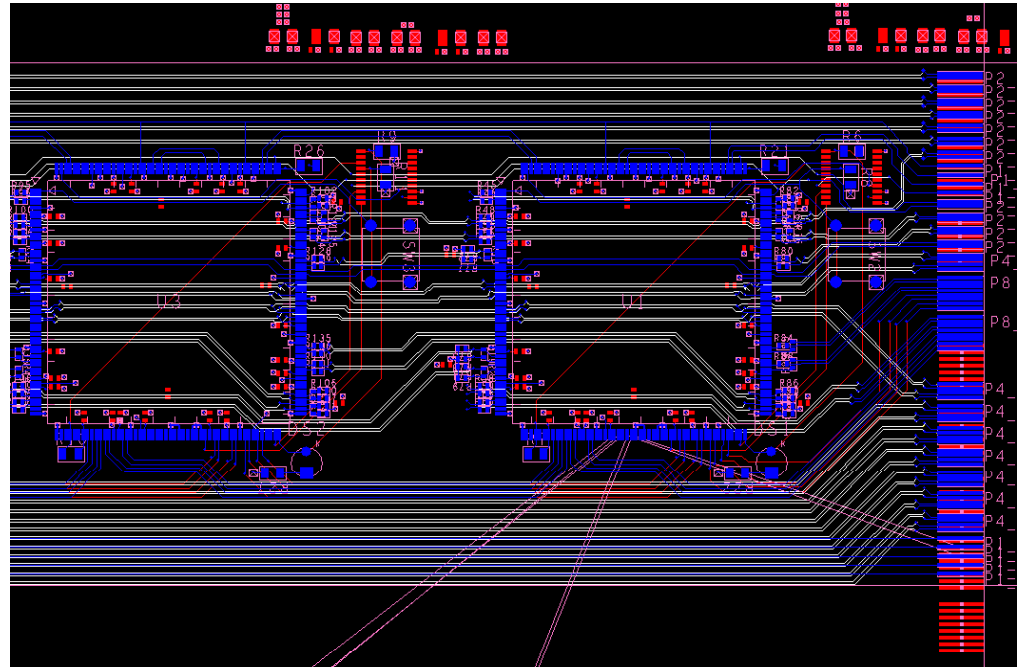
- Target slab PCB thickness = **800 μm**
- Expected thickness $\sim 770\mu\text{m}$ + resist + text
- Top, bottom and differential signal layers
- 5 power and ground planes
- Transmission line parameters from traces important for noise and power

Trace width (μm)	C_0 (pF/m)	Z_0 (Ω)
200	373	16.5
150	305	20.3
100	229	27.1
75	160	32.8



Slab panel model

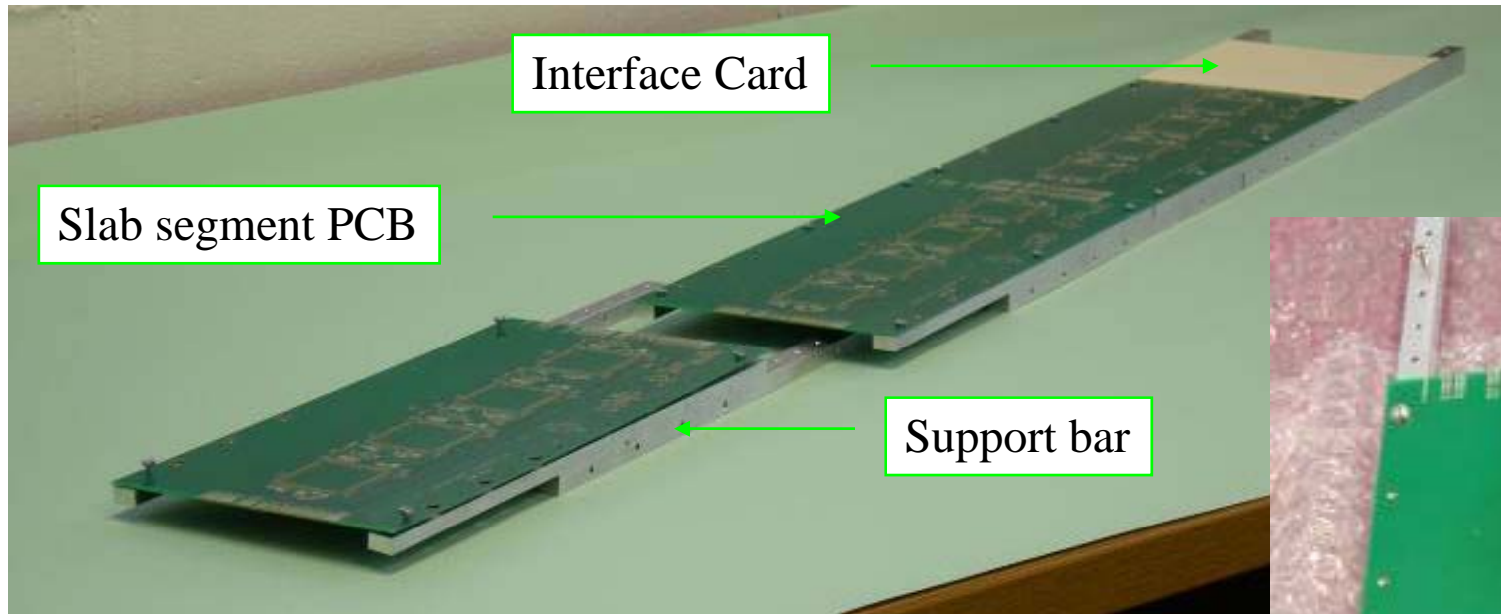
- FPGAs instead of VFE chips;
“pseudo-VFE” (pVFE)
- 1 FPGA mimics 2 VFE chips
- HCAL in VHDL serves as VFE



- Many signal distribution/routing options incorporated in PCB
- Many output standards and speeds supported by FPGA
- Includes long, folded lines for measurements on transmission lines



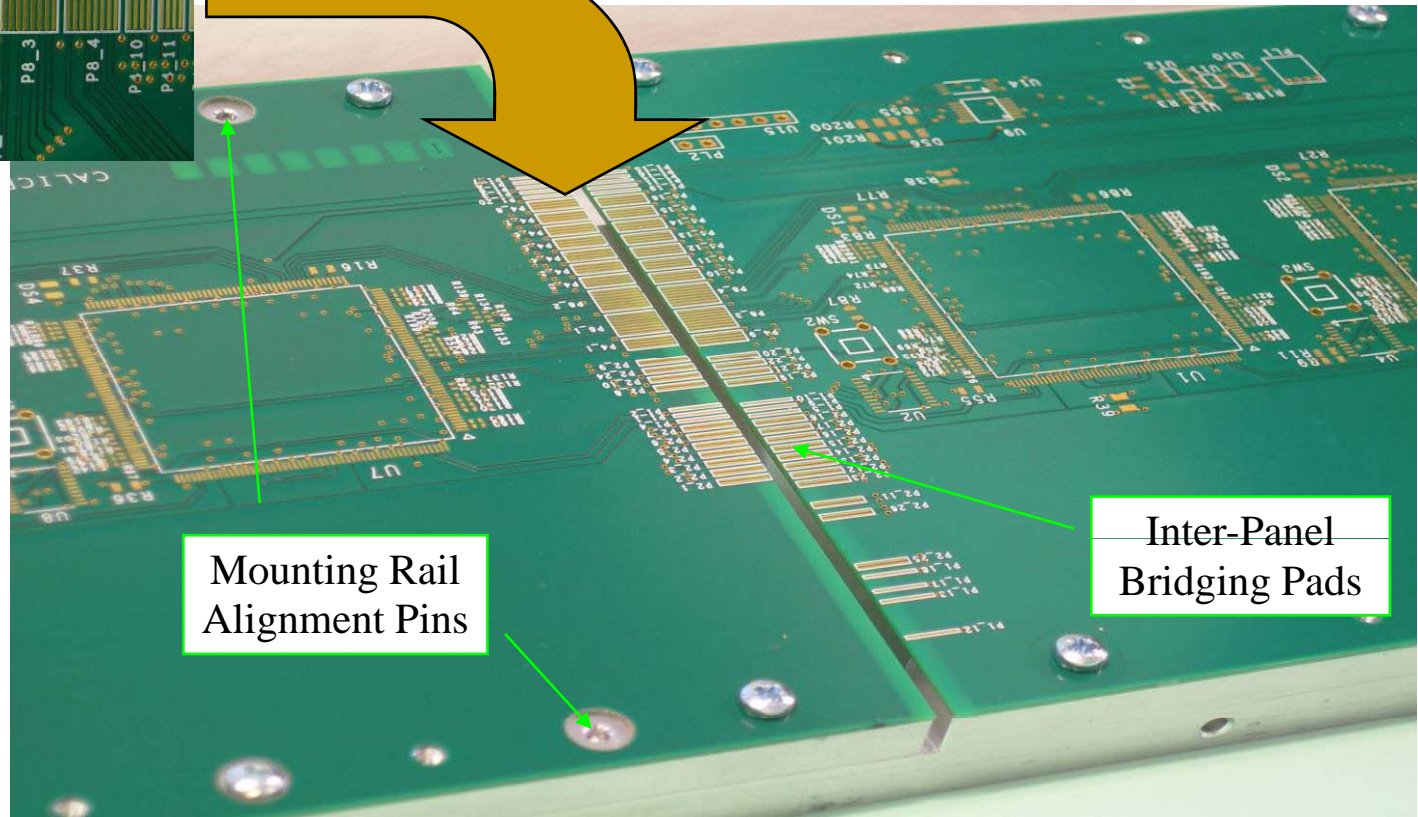
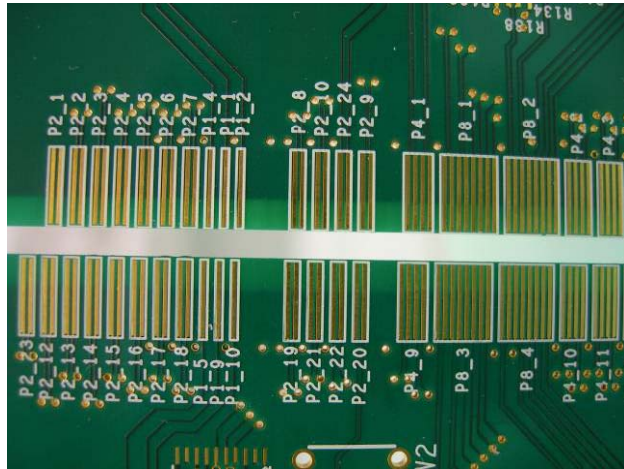
Slab model: current status



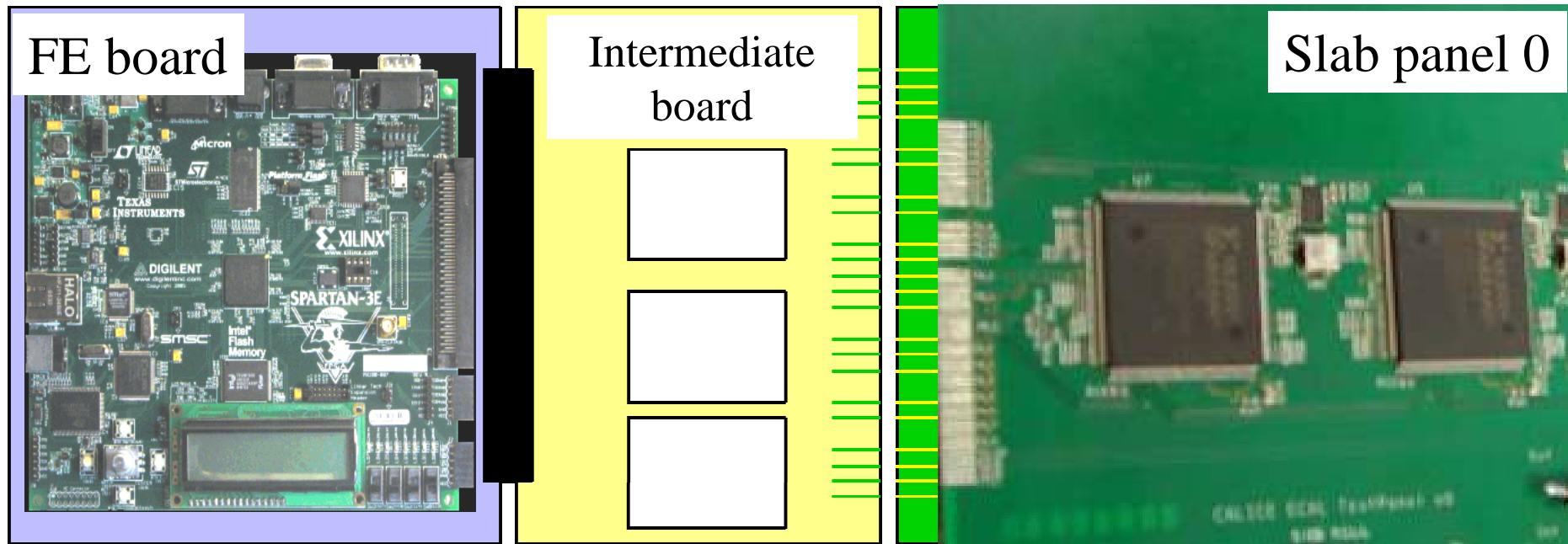
- **10 PCBs** manufactured
- PCB support bars for slab assembly
- 1 PCB populated, powered and tested

Slab panel PCB interconnects

- Test methods for interconnect



Slab panel test setup



- Clock generation
- Control signals (token, etc.)
- Data reception & buffering
- Interface with outside world
- Clock distribution
- Power distribution
- Interface with slab

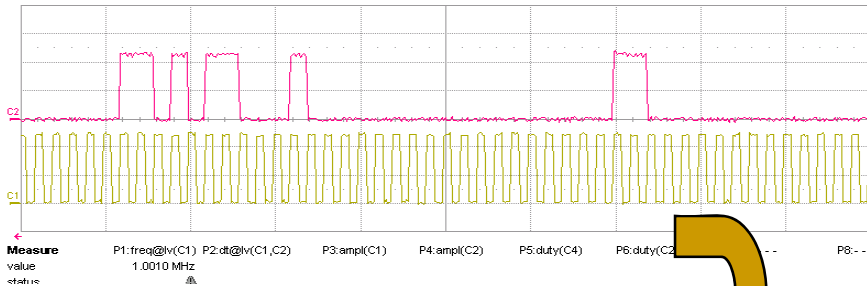
Digilent FPGA development board starter kit serves as FE board for tests

- Combines functions of LDA and system-dependent DIF of “real” system

Test slab current status

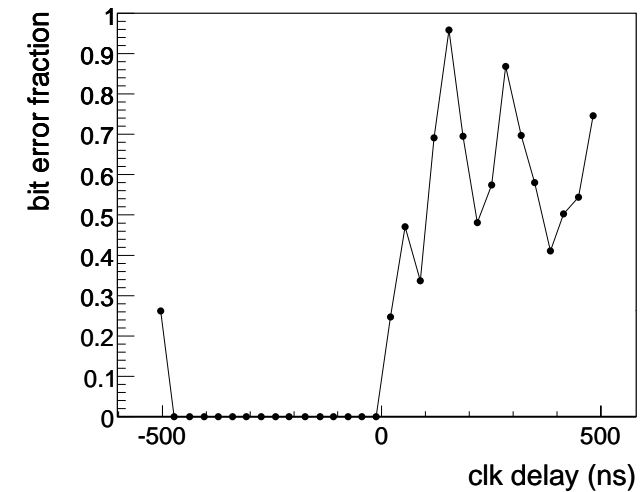
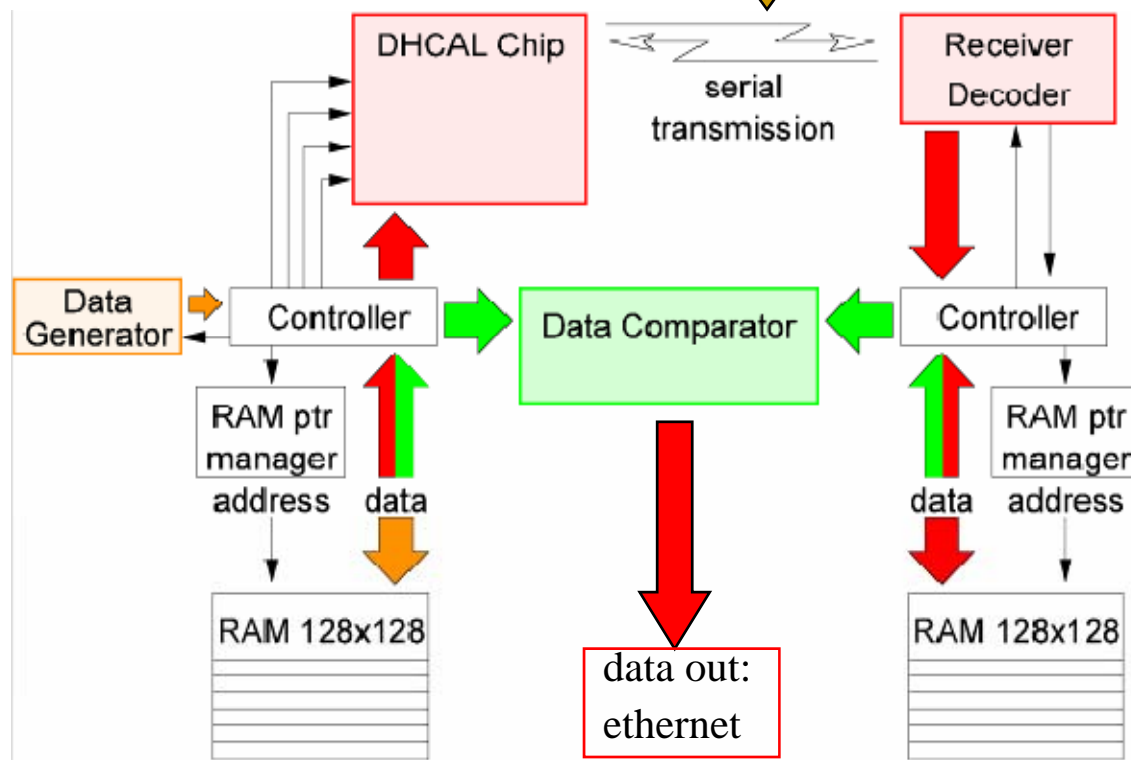
- Slab panel
 - One panel populated and tested
 - Firmware for pVFA FPGAs is effectively ready
- Intermediate board
 - Powered up OK, currently being tested
- FE board
 - Firmware: clock management, deserialiser, data buffer and ethernet communication works
- Slab ↔ intermediate board ↔ FE board
 - Connected, ready for commissioning
 - Assembling automated measurement system

pVFE and FE firmware: BER test



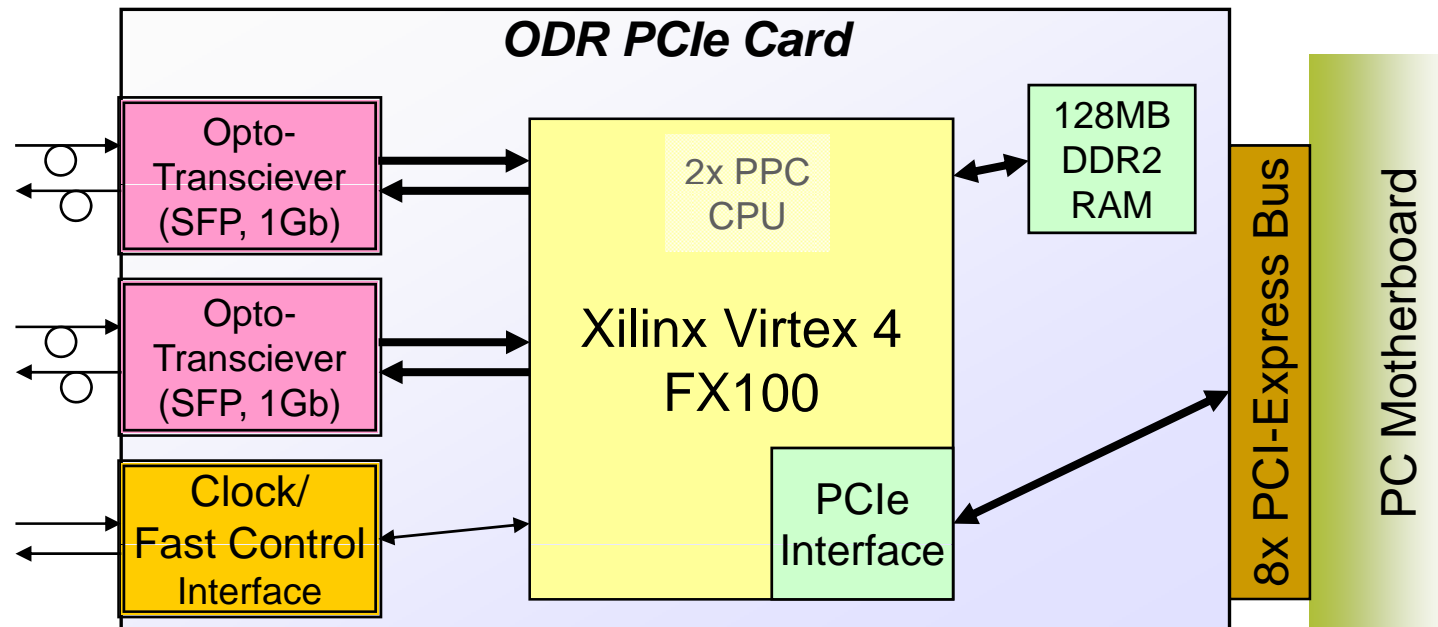
First Bit Error Rate (BER) test:

- ✓ All logic in single FPGA
- ✓ Separated Tx/Rx blocks
- ✓ Signals routed through external wires



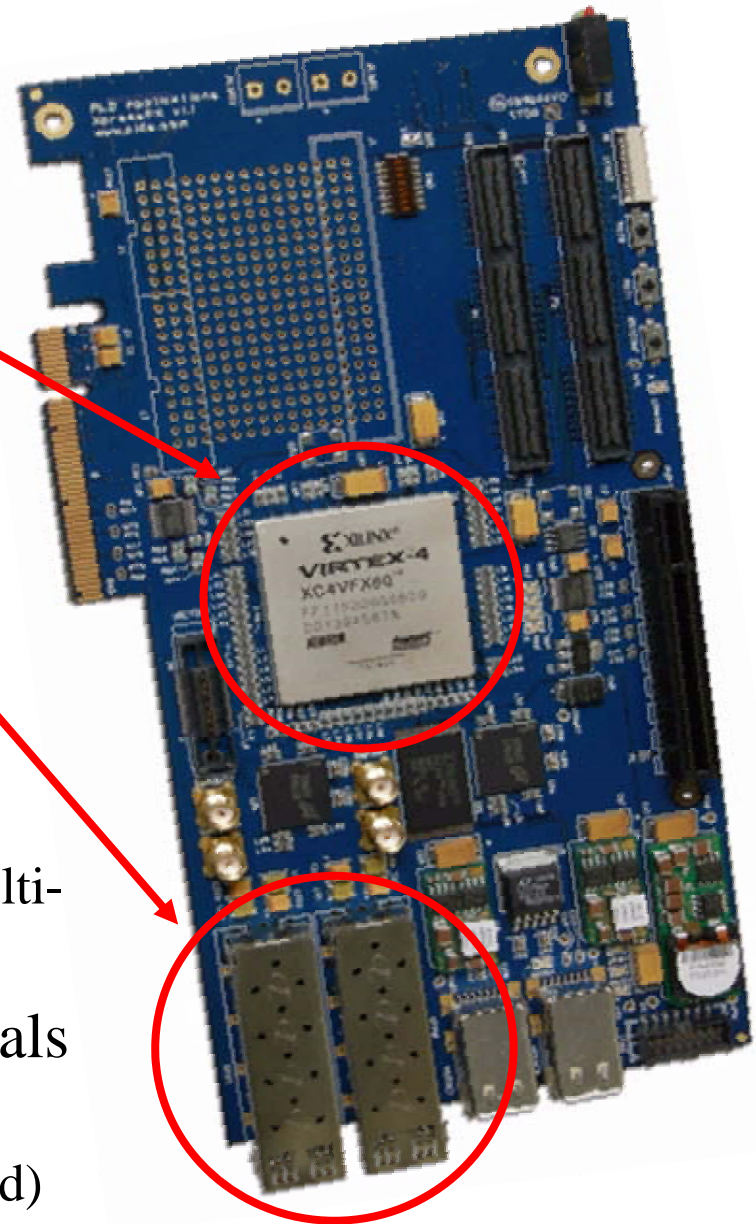
Off-Detector Receiver (ODR)

- Want readout optical fibres to go directly into PCs
 - No crates/custom electronics off-detector
 - Preferably off-the-shelf, commercially available
- **“Straw-man” choice** of card for data collection into PCs
 - Will be used for EUDET but specs expected to improve in near future



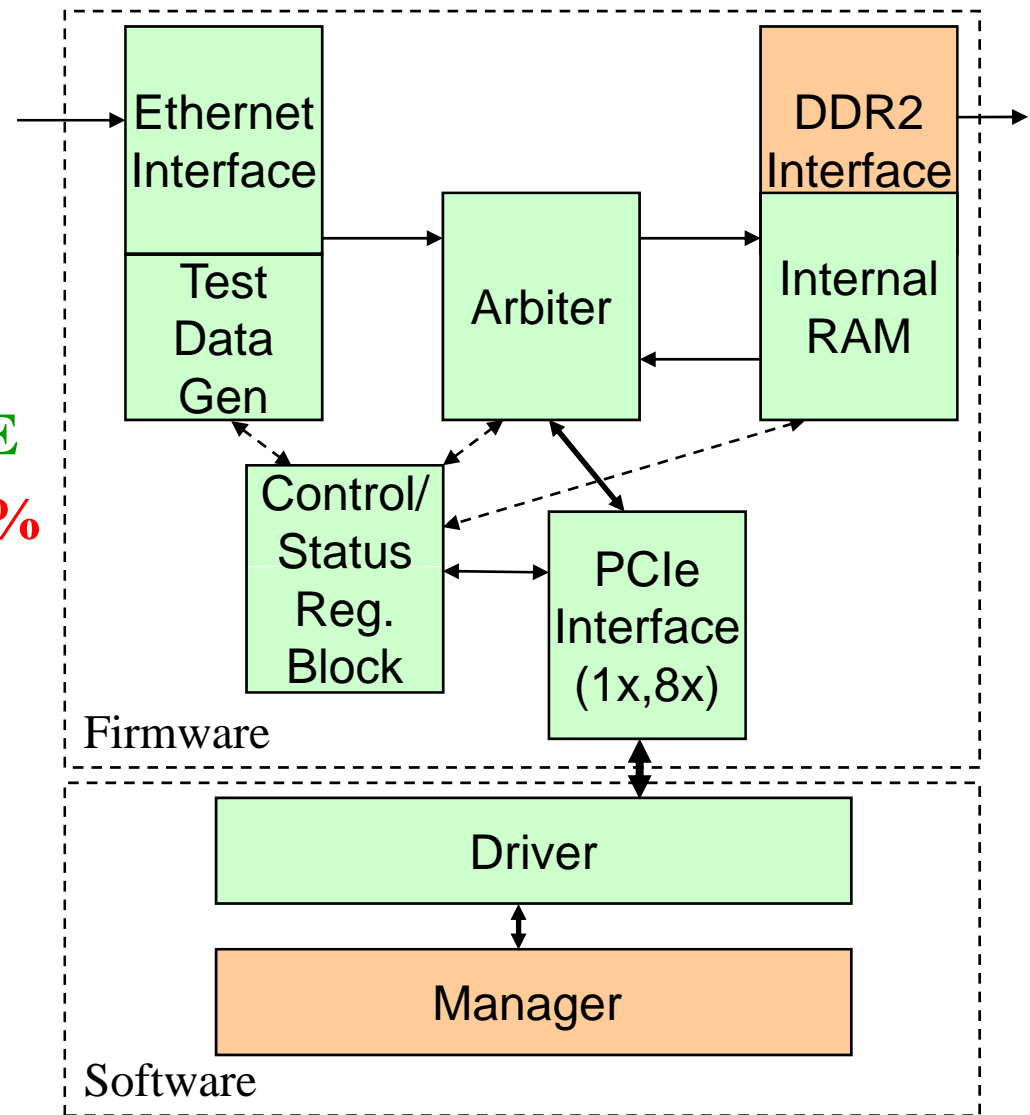
PLDA XpressFX

- PCI-Express Card
 - 8 lanes to PC
- Virtex 4, FX100 FPGA
 - Large FPGA; easily sufficient
- Hosts opto-links
 - 2×SFP on board
 - 3×SFP via commercial expansion board
 - 1.0–2.5Gb/sec optical inputs
- Distribution of clock and control
 - Initially copper (LVDS); later fibre
 - External clock and synch signals for multi-board synchronous operation
- Control may need fixed latency signals
 - Work needed to see if possible with this board (or if needs custom daughter board)



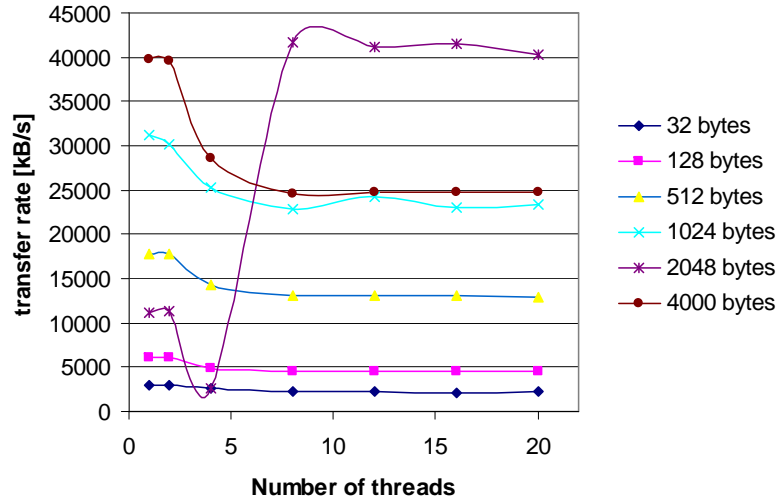
ODR status

- PCI-Express interface (1x,8x) **DONE**
- Register read/write **DONE**
- DMA access **DONE**
- Gbit (Ethernet) interface **DONE**
- Gbit (fixed latency) interface **0%**
- DDR2 interface **50%**
- Linux driver **DONE**
- Optimised disk store **50%**
- Manager software **50%**
- Performance profiling **50%**
- Clock and control uplink **20%**
- Fast controls interface **0%**

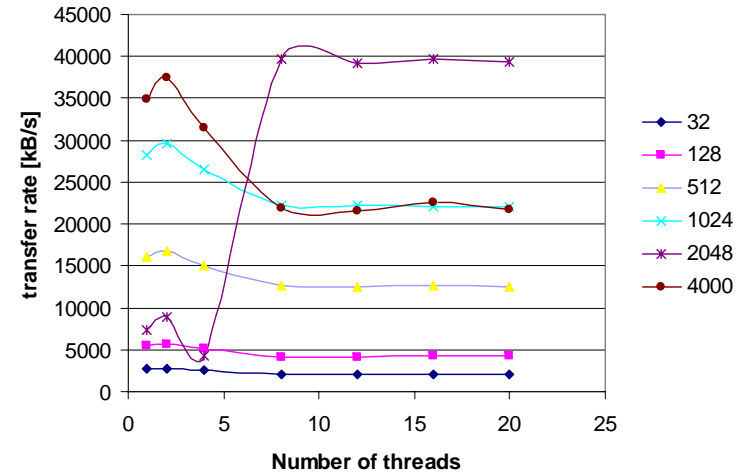


ODR performance

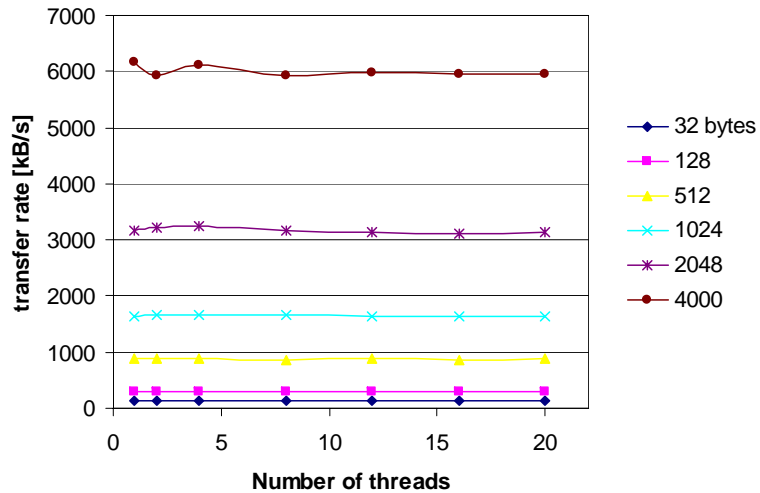
DMA only



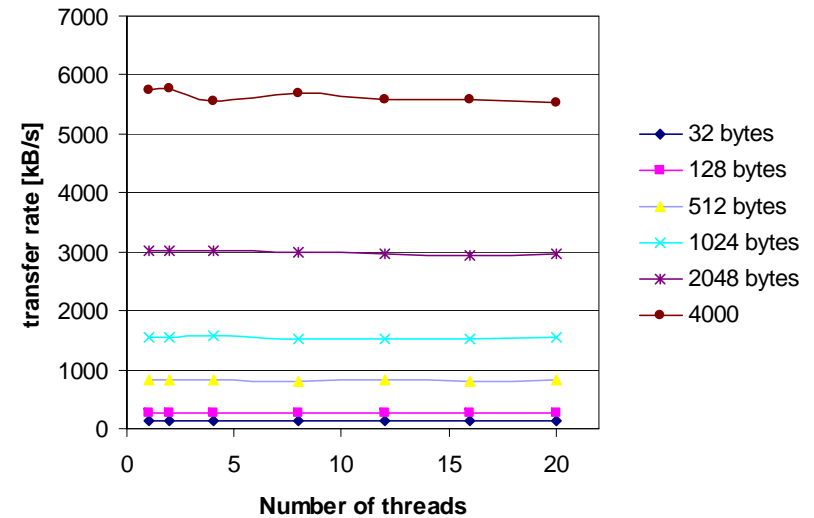
DMA, dir creation



DMA, file/dir creation, no data write

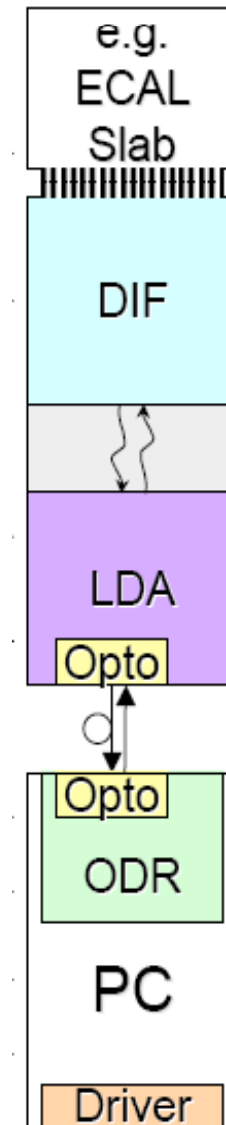


DMA, data written to the disk



LDA-DIF interface

- ODR is most expensive part of system
 - Minimise number of ODRs and optical links
- LDAs controlled directly from ODR
 - Two optical links = two LDAs per ODR
- The major **fanout** will be at LDA-DIF connection
 - Simple serial I/O interface; up clock/data, down data?
 - Could have ~50 DIFs per LDA
 - Resulting DIF data rate $(1\text{Gb/sec})/50 \sim 20\text{Mb/sec}$; enough?
- LDA-DIF interface is current focus
 - Must define this clearly soon to allow work on both sides to continue in parallel
 - Need to know **requirements** for data rates, fan-out numbers, clock frequencies, clock jitter, fixed latency, etc.
 - Hope to firm all this up within the next month



Summary

- Significant effort ongoing to understand how to build an ECAL **slab PCB** for EUDET and/or a final ILC detector
 - Getting a PCB to meet all the specs will be a major task...
 - ...but we are developing the expertise within CALICE to do this
- Straw-man **off-detector receiver** being tested
 - Will be used for EUDET; technology will move on for final detector
 - Much of the required firmware and software are ready
 - One outstanding issue is ability to run with fixed latency for clock and control
- **LDA-DIF interface** is a hot topic
 - Input needed from the various subdetectors over next few weeks